

Applicant : Jeffrey H. Burns
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In the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) An optical sensor circuit assembly, comprising:
an optically transmissive substrate, an electrical circuit on the optically transmissive substrate, the electrical circuit including electrically conductive leads; ~~including filter~~ material[[:]] and
an integrated circuit including an optical imaging element and electrically conductive pads on a face of the integrated circuit; and
the optical imaging element electrically coupled to the electrical circuit on the said substrate by an electrical connection between the electrically conductive pads on the face of the integrated circuit and the electrically conductive leads of the electrical circuit on the substrate.
2. (Currently Amended) The optical sensor circuit assembly of claim 1, wherein the optically transmissive substrate includes filter material, said filter material is embedded in said substrate.
3. (Currently Amended) The optical sensor circuit assembly of claim 1, wherein the optically transmissive substrate includes filter material, said filter material is dispersed in said substrate.
4. (Currently Amended) The optical sensor circuit assembly of claim 1, wherein the optically transmissive substrate includes filter material, said filter material ~~comprises~~ comprising a thin film layer on said the substrate.
5. (Original) The optical sensor circuit assembly of claim 4, wherein said thin film layer further comprises material having antireflective properties.
6. (Canceled).

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7. (Canceled).

8. (Currently Amended) The optical sensor circuit assembly of claim [[7]] 1, wherein the optical imaging element is electrically coupled to the integrated circuit by electrically further comprising a conductive bump bumps disposed between said plurality of the leads and said plurality of the pads.

9. (Original) The optical sensor circuit assembly of claim 1, further comprising at least one optical element positioned to direct electromagnetic radiation through said substrate and filter material and to said optical imaging element.

10. (Original) The optical sensor circuit assembly of claim 9, further comprising a lens mount supporting said at least one optical element and coupled to a second surface of said substrate.

11.-19. (Canceled).